SONY

Ver.1.0

IMX662-AAMR

Diagonal 6.45 mm (Type 1/2.8) CMOS Solid-state Image Sensor with Square Pixel for Monochrome Cameras

Description

The IMX662-AAMR is a diagonal 6.45 mm (Type 1/2.8) CMOS active pixel type solid-state image sensor with a square pixel array and 2.12 M effective pixels. This chip operates with analog 3.3 V, digital 1.1 V, and interface 1.8 V triple power supply, and has low power consumption. High sensitivity, low dark current and no smear are achieved. This chip features an electronic shutter with variable charge-integration time. (Application: Security cameras)

Features

- CMOS active pixel type dots
- Built-in timing adjustment circuit, H/V driver and serial communication circuit
- Input frequency: 24 MHz / 27 MHz / 37.125 MHz / 72 MHz / 74.25 MHz
- ♦ Number of recommended recording pixels: 1920 (H) × 1080 (V) approx. 2.07M pixel
- ♦ Readout mode
 All-pixel scan mode
 - 2×2 adjacent pixel binning mode
 - Window cropping mode
 - Horizontal / Vertical direction Normal / Inverted readout mode
- ♦ Readout rate Maximum frame rate in All-pixel scan mode: 12 bit: 60 frame/s, 10 bit: 90 frame/s
- High dynamic range (HDR) function
 Digital overlap HDR
 Clear HDR
- Synchronizing sensors function
- ◆ Variable-speed shutter function (resolution 1H unit)
- ◆ 10-bit / 12-bit A/D converter
- CDS / PGA function

0 dB to 30 dB: Analog Gain 30 dB (step pitch 0.3 dB)

30.3 dB to 72 dB: Analog Gain 30 dB + Digital Gain 0.3 dB to 42 dB (step pitch 0.3 dB)

Supports I/O
 CSI-2 serial data output (2 Lane / 4 Lane)
 RAW10 / RAW12 output

STARVIS 2

* STARVIS 2 and its logo are registered trademarks or trademarks of Sony Group Corporation or its affiliates. The STARVIS 2 is back-illuminated pixel technology used in CMOS image sensors for security camera applications. It features a sensitivity of 2000 mV or more per 1 µm2 (color product, when imaging with a 706 cd/m2 light source, F5.6 in 1 s accumulation equivalent). It also has a wide dynamic range (AD 12 bit) of more than 8 dB compared to STARVIS for the same pixel size in a single exposure, and achieves high picture quality in the visible-light and near infrared light regions.

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Device Structure

♦ CMOS image sensor	
♦ Image size	Diagonal 6.45 mm (Type 1/2.8) approx. 2.12 M pixels, All pixels
♦ Total number of pixels	1936 (H) × 1120 (V) approx. 2.16 M pixels
Number of effective pixels	1936 (H) × 1100 (V) approx. 2.12 M pixels
◆ Number of active pixels	1936 (H) × 1096 (V) approx. 2.12 M pixels
Number of recommended recording pixels	1920 (H) × 1080 (V) approx. 2.07 M pixels
♦ Unit cell size	2.9 μm (H) × 2.9 μm (V)
♦ Optical black	Horizontal (H) direction: Front 0 pixels, rear 0 pixels
	Vertical (V) direction: Front 20 pixels, rear 0 pixels
◆ Dummy	Horizontal (H) direction: Front 0 pixels, rear 0 pixels
	Vertical (V) direction: Front 0 pixels, rear 0 pixels
◆ Package	114 pin LGA

Image Sensor Characteristics

(Tj = 60 °C)

Item		Value	Remarks	
Sensitivity	Тур.	29300 Digit/lx/s	12 bit converted value	
Saturation signal	Min.	3895 Dight	12 bit converted value	

Basic Drive Mode

Drive mode	Recommended number of recording pixels	Maximum frame rate [frame/s]	Output interface	ADC [bit]
All-pixel	1920 (H) × 1080 (V) approx. 2.07 M pixels	90	CSI-2	10
2×2 adjacent pixel binning mode	960 (H) × 540 (V) approx. 0.51 M pixels	90	CSI-2	10

